

### **Amendments to the Specification:**

On page 1 replace the paragraph entitled "Background of the Invention" with the following paragraphs:

#### **-Priority Claim**

This is a U.S. national stage entry of application No. PCT/DE00/00384, filed on February 10, 2000.

#### **Background of the Invention**

Reactive, solvent-free adhesives cross-linkable with moisture from the air, particularly hot-melt adhesives, are well known in the state of the art. Such adhesives are prepared from low-molecular starting materials comprising OH groups, such as polyesters or polyethers, which are then converted to reactive isocyanate-terminated adhesives with a stoichiometric excess of isocyanates. 4,4'-diisocyanatodiphenylmethane (MDI), 1,5-diisocyanatodiphenylmethane (NDI), 1,6-diisocyanatohexane (HDI), 2,4-diisocyanatotoluene (TDI), 1-isocyanato-3-isocyanatomethyl-3,5,5-trimethylcyclohexane (IPDI) or their prepolymers can be used as isocyanate components.--.

On page 6 replace the third full paragraph with the following paragraph:

Resins which can be used in the first and/or second adhesive component (such as e.g. aliphatic, cyclic or cycloaliphatic hydrocarbon resins, terpene phenol resins, cumaroneindene resins,  $\alpha$ -methyl styrene resins, polymerized tall resin ester or ketone aldehyde resins) are not particularly limited. However, resins having low acid numbers, particularly having values lower than 1 mg KOH/g, are preferably used. The contents or amounts of resin(s) in the first and/or second adhesive component can, for example, preferably be about 5 to 35 wt.% and generally between 0 and 70 wt.%.